

## HOW TO REACH US

FRAUNHOFER INSTITUTE FOR  
ELECTRONIC NANO SYSTEMS ENAS

MAY 21 AND 22, 2019 | FRAUNHOFER ENAS  
TECHNOLOGIE-CAMPUS 3 | 09126 CHEMNITZ

## CHEMNITZER SEMINAR MEMS TECHNOLOGIES AND APPLICATIONS

### Registration:

The registration is free of charge.

Please send an e-mail for registration with the information whether you would like to attend both days or only one (May 21 or 22) to [chemnitzer.seminare@enas.fraunhofer.de](mailto:chemnitzer.seminare@enas.fraunhofer.de) until May 3, 2019.

### Hotel:

Until April 16, rooms in Hotel Chemnitzer Hof can be ordered by using the keyword: Seminar System Packaging.

single room (incl. breakfast): 69 EUR

Hotel Chemnitzer Hof, Theaterplatz 4, 09111 Chemnitz

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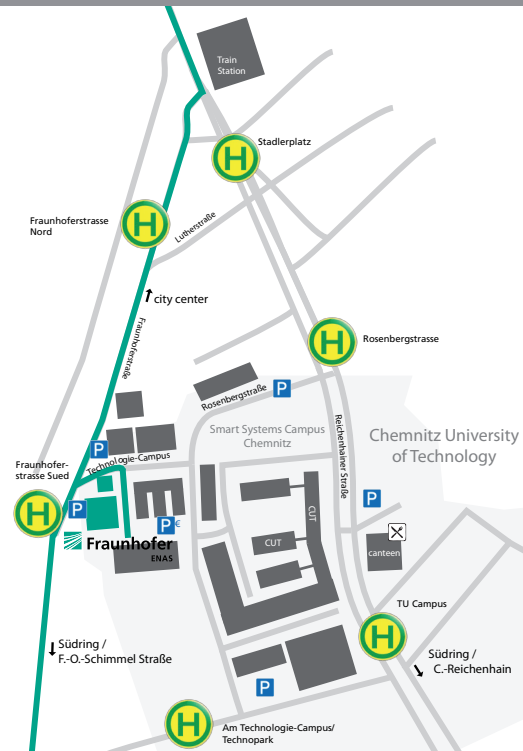
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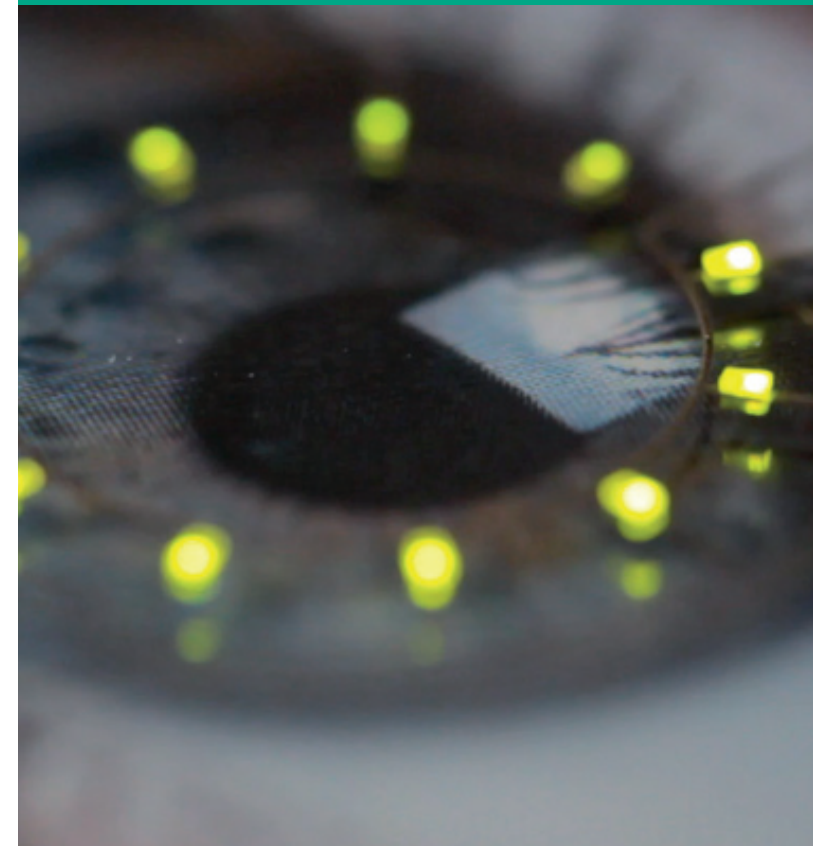
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# PROGRAM



## CHEMNITZER SEMINAR »MEMS TECHNOLOGIES AND APPLICATIONS«

Smart systems are becoming more and more important in our daily life, e.g. in cars, security applications, medical engineering, condition monitoring, logistics and other applications. A major bottleneck, however, is the integration and packaging of the sensitive microstructures on different levels to allow them to withstand even harsh environments and meet the competitive market requirements. In 2019 advanced MEMS and MEMS packaging technologies as well as current integration trends and national/international funding possibilities will be highlighted within the 32nd Chemnitzer Seminar.

### TUESDAY MAY 21, 2019

- 12:30 – 12:40 pm **Welcome** | Dr. Maik Wiemer, Fraunhofer ENAS
- 12:40 – 1:10 pm **Keynote: Trends and Challenges in MEMS Integration** | Amandine Pizzagalli, Yole Développement
- 1:10 – 1:40 pm **MEMS based Photo-Acoustic Gas Sensor** | Dr. Rainer Schaller, Infineon Technologies AG
- 1:40 – 2:10 pm **Organic and Flexible Sensors in Applications** | Dr. Dominik Gronarz, Organic Electronics Saxony Management GmbH
- 2:10 – 2:50 pm Poster and Demonstrator Presentation, Coffee Break and Networking
- 2:50 – 3:20 pm **Keynote: Quality and Reliability Testing of Wirebonds – Limitations and New Opportunities** | Stefan Schmitz, Bond-IQ GmbH
- 3:20 – 3:50 pm **Advanced Surface Micromachining Process – a First Step towards 3D MEMS** | Dr. Jörg Bräuer, Robert Bosch GmbH
- 3:50 – 4:20 pm **Capacitive Micromachined Ultrasonic Transducers for Medical and Non-Medical Applications** | Dr. Nooshin Saeidi, Fraunhofer ENAS
- 4:20 – 4:50 pm **Transferring Research Knowledge to Clinical Practice – Challenges and Chances** | Dr. Marcus Binner, TissueGUARD Team

### WEDNESDAY MAY 22, 2019

- 8:30 – 8:40 am **Welcome** | Dr. Maik Wiemer, Fraunhofer ENAS
- 8:40 – 9:10 am **Keynote: From Sampling to Ramping – Technology and Business Model Challenges for MEMS Foundries to Address WLP Applications** | Stefan Ernst, X-FAB Semiconductor Foundries AG
- 9:10 – 9:40 am **USeP: Universal sensor platform for IoT applications** | Marco Meinig, Fraunhofer ENAS
- 9:40 – 10:10 am **Electrodeposition of Aluminum Towards Wafer-Level Al-Al Thermocompression Bonding** | Silvia Hertel, Fraunhofer ENAS
- 10:10 – 10:40 am Poster and Demonstrator Presentation, Coffee Break and Networking
- 10:40 – 11:10 am **Current Funding Opportunities in Electronics and MEMS** | Dr. Gregor Schwartz, VDI/VDE Innovation + Technik GmbH
- 11:10 – 11:40 am **3D Printed Electronics for Mechatronic Systems** | Dr. Martin Hedges, Neotech AMT GmbH
- 11:40 – 12:10 pm **Building-in Reliability into Power Modules** | Dr. Jacek Rudzki, Danfoss Silicon Power GmbH
- 12:10 – 12:40 pm Discussion and end of workshop
- 12:40 – 2:00 pm Lunch
- from 2:00 pm Individual Lab and Window Tours